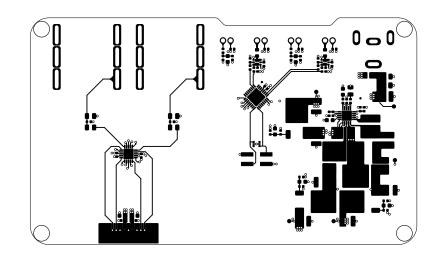
REVISION HISTORY

Rev. A INITIAL RELEASE



## BOARD CHARACTERISTICS

Copper Layer Count: 6 Board Thickness: 1.6000 mm

Board overall dimensions: 102.3000 mm x 60.0000 mm

Min track/spacing:0.0900 mm / 0.0900 mmMin hole diameter:0.2500 mmCopper Finish:ENIGImpedance Control:NoCastellated pads:NoPlated Board Edge:No

Edge card connectors: No

| Lage cara commercial |                 |                     |               |                |               |           |              |  |  |
|----------------------|-----------------|---------------------|---------------|----------------|---------------|-----------|--------------|--|--|
|                      | Layer Name      | Туре                | Material      | Thickness (mm) | Color         | Epsilon R | Loss Tangent |  |  |
|                      | F.Silkscreen    | Top Silk Screen     | Not specified | 0 mm           | White         | 1         | 0            |  |  |
| 1                    | F.Paste         | Top Solder Paste    |               | 0 mm           |               | 1         | 0            |  |  |
|                      | F.Mask          | Top Solder Mask     | Not specified | 0.01 mm        | Green         | 3.3       | 0            |  |  |
|                      | F.Cu (Signal)   | copper              |               | 0.035 mm       |               | 1         | 0            |  |  |
|                      | Dielectric      | prepreg             | FR4           | 0.1 mm         | Not specified | 4.5       | 0.02         |  |  |
|                      | In1.Cu (Ground) | copper              |               | 0.0152 mm      |               | 1         | 0            |  |  |
|                      | Dielectric      | core                | Copper        | 0.5548 mm      | #D2960FFF     | 4.5       | 0.02         |  |  |
|                      | In2.Cu (Signal) | copper              |               | 0.0152 mm      |               | 1         | 0            |  |  |
|                      | Dielectric      | prepreg             | FR4           | 0.1 mm         | Not specified | 4.5       | 0.02         |  |  |
|                      | In3.Cu (Ground) | copper              |               | 0.035 mm       |               | 1         | 0            |  |  |
|                      | Dielectric      | core                | FR4           | 0.5548 mm      | Not specified | 4.5       | 0.02         |  |  |
|                      | In4.Cu (Power)  | copper              |               | 0.035 mm       |               | 1         | 0            |  |  |
|                      | Dielectric      | prepreg             | FR4           | 0.1 mm         | Not specified | 4.5       | 0.02         |  |  |
|                      | B.Cu (Ground)   | copper              |               | 0.035 mm       |               | 1         | 0            |  |  |
|                      | B.Mask          | Bottom Solder Mask  | Not specified | 0.01 mm        | Green         | 3.3       | 0            |  |  |
|                      | B.Paste         | Bottom Solder Paste |               | 0 mm           |               | 1         | 0            |  |  |
|                      | B.Silkscreen    | Bottom Silk Screen  | Not specified | 0 mm           | White         | 1         | 0            |  |  |
|                      |                 |                     |               |                |               |           |              |  |  |

NOTES: UNLESS OTHERWISE SPECIFIED

1: MANUFACTURE TO IPC CLASS 2

| 1590N1 BASEBOARD – PCBA |             | PCB           |              | RELEASED |     |   |
|-------------------------|-------------|---------------|--------------|----------|-----|---|
| © Alessandro Rizzoni    | APPROVED BY | REVISION<br>A | DATE OF ISSU | -        | 1/1 | ] |
| A                       |             |               |              |          |     | 1 |

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